

MA62

Silicon NPN Trigger Device for Thyristor

Trigger Device for Thyristor

■ Features

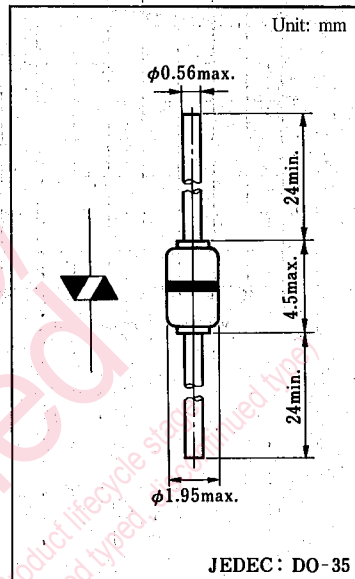
- Symmetrical breakover voltage characteristics
- High output voltage, low breakover current

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Average Power Dissipation	P_{AV}	150	mW
Peak Current	I_{PM}^*	2	A
Operating Ambient Temperature	T_{opr}	100	°C
Storage Temperature	T_{stg}	-55 ~ +125	°C

* $T_a < 50^\circ\text{C}$, $t < 10\mu\text{s}$, Repetitive frequency 60Hz

■ Package Dimensions



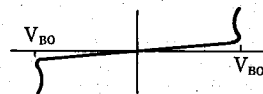
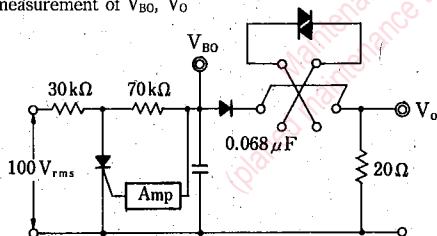
■ Electrical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Breakover Voltage	V_{BO}^{*1}	$I = I_{BO}$	28		36	V
Output Voltage	V_o^{*1}		4	6.3		V
Breakover Current	I_{BO}	$V = V_{BO}$		10	100	μA
Temperature Coefficient of Breakover Voltage				0.1		%/°C
Breakover Voltage Deviation	ΔV_{BO}^{*2}				2.5	V

© Input and output frequency of ratings: 100MHz

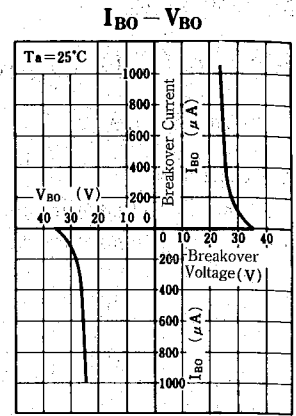
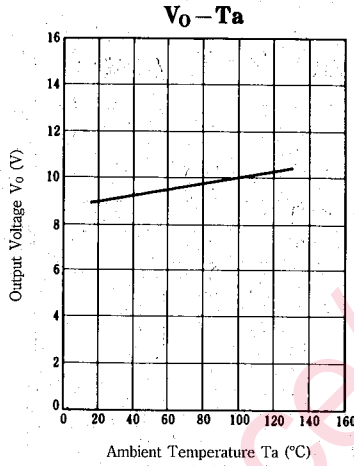
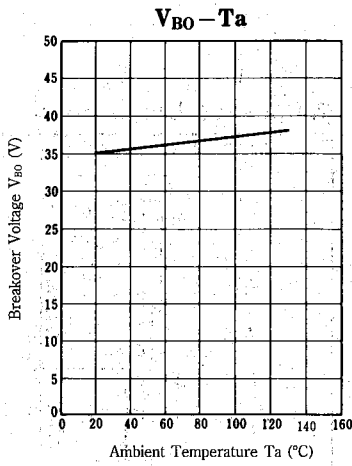
* 2 Symmetrical characteristics of V_{BO}

* t_{tr} measurement of V_{BO} , V_o



■ Marking Symbol

Type No.	MA62
Color	Black



Maintenance Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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